	Material Comp © Copyright 2005. II International and Part	PC, Bannockb	ourn, Illinois. A	All rights reserved untions.	nder both	This docume level parts, t	ent is a declarat he declaration	ion of the	ne substances asses all low	within the er level mat	manufactur erials for wl	er listed it hich the m	tem. Note: nanufacture	if the item is an as or has engineering	ssembly with lowe responsibility.	
1752-21.1					Form Type Distribute	 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater 					eous Materia	ials and Mfg Information				
Supplie	r Information															
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
nsemi												2023-06-08				
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*						
Product-l	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item Number DFB20100		Number Mfr Item Name				Effective Date Version Manufacturing Site 2023-06-08 TSCBE		ring Site	V	Weight*	UOM	Unit Type			
			00	BR TS6P GPPN 20A 1000V						7	7671.0	mg	Each			
/anufa	cturing Proccess Informat	tion														
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 M		J-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperat	ure Num	ber of Reflow Cyc	cles		
	Matte Tin (Sn) - annealed		U Alloy NA			0 C		30		secon	ds 3					
omments	3															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	200.0	mg	Supplier	Silver (Ag)	7440-22-4		5	mg
			А	Lead (Pb)	7439-92-1	7a	185	mg
			Supplier	Tin (Sn)	7440-31-5		10	mg
umper	60.4	mg	Supplier	Iron (Fe)	7439-89-6		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		60.34	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Lead Frame	2315.0	mg	Supplier	Iron (Fe)	7439-89-6		1.852	mg
			Supplier	Copper (Cu)	7440-50-8		2312.6851	mg
			Supplier	Phosphorus (P)	7723-14-0		0.463	mg
Mold Compound-Black	4807.0	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		96.14	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		721.05	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		96.14	mg
			Supplier	Carbon Black (C)	1333-86-4		48.07	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		480.7	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3364.8999	mg
Plating	248.6	mg	Supplier	Tin (Sn)	7440-31-5		248.6	mg
Silicon Dice	40.0	mg	Supplier	Silicon (Si)	7440-21-3		39.992	mg
			В	Nickel (Ni)	7440-02-0		0.004	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg